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Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	In-System Reprogrammable™ (ISR™) CMOS
Delay Time tpd(1) Max	15 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	-
Number of Macrocells	128
Number of Gates	-
Number of I/O	133
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	160-LQFP
Supplier Device Package	160-TQFP (24x24)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/cy37128vp160-83axi

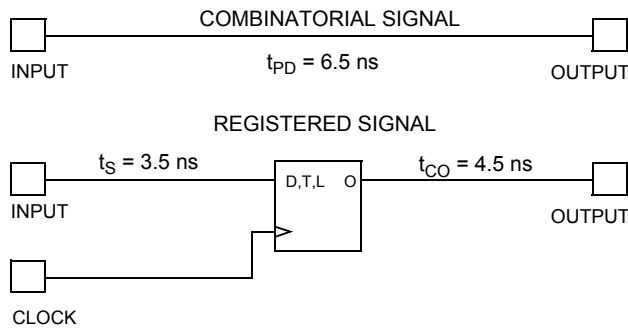


Figure 5. Timing Model for CY37128

JTAG and PCI Standards

PCI Compliance

5V operation of the Ultra37000 is fully compliant with the PCI Local Bus Specification published by the PCI Special Interest Group. The 3.3V products meet all PCI requirements except for the output 3.3V clamp, which is in direct conflict with 5V tolerance. The Ultra37000 family's simple and predictable timing model ensures compliance with the PCI AC specifications independent of the design.

IEEE 1149.1-compliant JTAG

The Ultra37000 family has an IEEE 1149.1 JTAG interface for both Boundary Scan and ISR.

Boundary Scan

The Ultra37000 family supports Bypass, Sample/Preload, Extest, Idcode, and Usercode boundary scan instructions. The JTAG interface is shown in Figure 6.

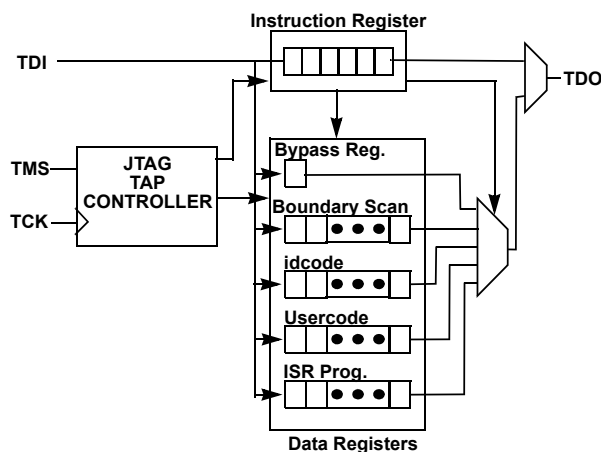


Figure 6. JTAG Interface

In-System Reprogramming (ISR)

In-System Reprogramming is the combination of the capability to program or reprogram a device on-board, and the ability to support design changes without changing the system timing or device pinout. This combination means design changes during debug or field upgrades do not cause board respins. The Ultra37000 family implements ISR by providing a JTAG compliant interface for on-board programming, robust routing

resources for pinout flexibility, and a simple timing model for consistent system performance.

Development Software Support

Warp

Warp is a state-of-the-art compiler and complete CPLD design tool. For design entry, Warp provides an IEEE-STD-1076/1164 VHDL text editor, an IEEE-STD-1364 Verilog text editor, and a graphical finite state machine editor. It provides optimized synthesis and fitting by replacing basic circuits with ones pre-optimized for the target device, by implementing logic in unused memory and by perfect communication between fitting and synthesis. To facilitate design and debugging, Warp provides graphical timing simulation and analysis.

Warp Professional™

Warp Professional contains several additional features. It provides an extra method of design entry with its graphical block diagram editor. It allows up to 5 ms timing simulation instead of only 2 ms. It allows comparison of waveforms before and after design changes.

Warp Enterprise™

Warp Enterprise provides even more features. It provides unlimited timing simulation and source-level behavioral simulation as well as a debugger. It has the ability to generate graphical HDL blocks from HDL text. It can even generate testbenches.

Warp is available for PC and UNIX platforms. Some features are not available in the UNIX version. For further information see the Warp for PC, Warp for UNIX, Warp Professional and Warp Enterprise data sheets on Cypress's web site (www.cypress.com).

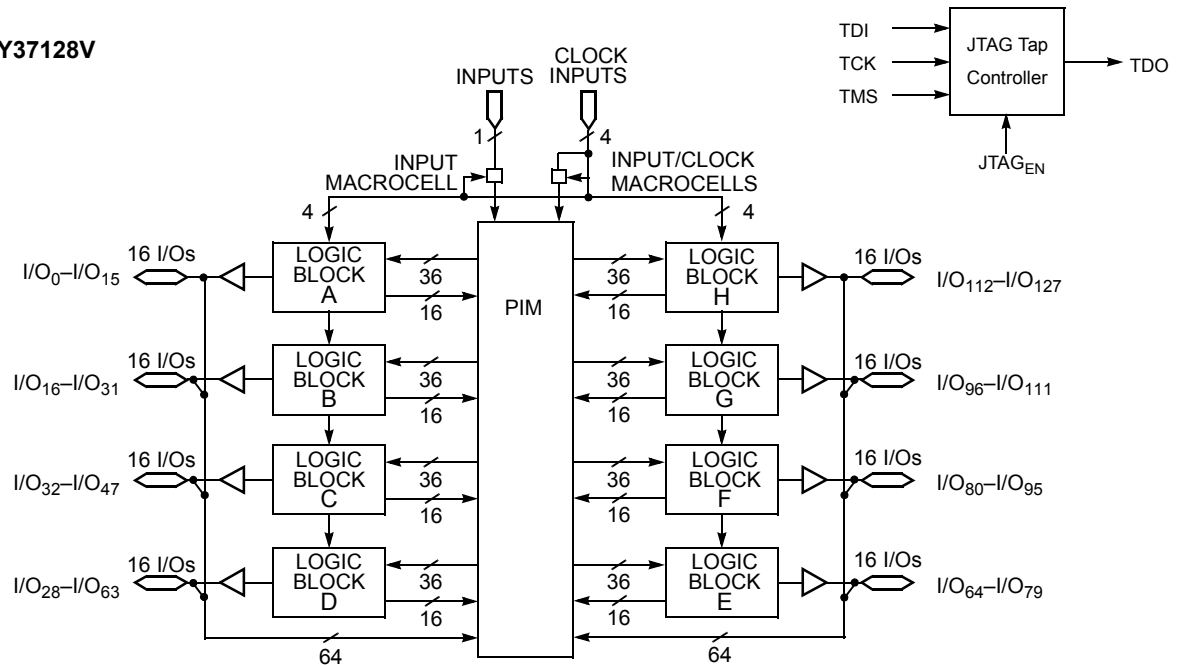
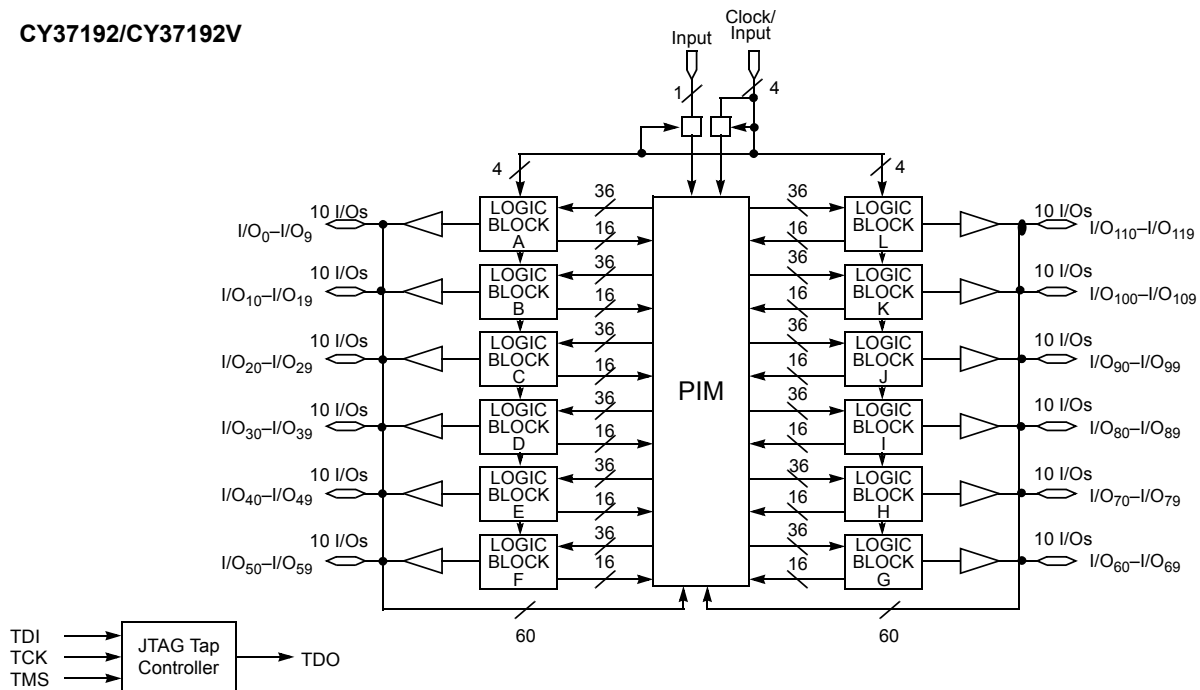
Third-Party Software

Although Warp is a complete CPLD development tool on its own, it interfaces with nearly every third party EDA tool. All major third-party software vendors provide support for the Ultra37000 family of devices. Refer to the third-party software data sheet or contact your local sales office for a list of currently supported third-party vendors.

Programming

There are four programming options available for Ultra37000 devices. The first method is to use a PC with the 37000 UltraISR programming cable and software. With this method, the ISR pins of the Ultra37000 devices are routed to a connector at the edge of the printed circuit board. The 37000 UltraISR programming cable is then connected between the parallel port of the PC and this connector. A simple configuration file instructs the ISR software of the programming operations to be performed on each of the Ultra37000 devices in the system. The ISR software then automatically completes all of the necessary data manipulations required to accomplish the programming, reading, verifying, and other ISR functions. For more information on the Cypress ISR Interface, see the ISR Programming Kit data sheet (CY3700i).

The second method for programming Ultra37000 devices is on automatic test equipment (ATE). This is accomplished through a file created by the ISR software. Check the Cypress website for the latest ISR software download information.

Logic Block Diagrams (continued)
CY37128/CY37128V

CY37192/CY37192V


5.0V Device Characteristics

Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature -65°C to +150°C

Ambient Temperature with

Power Applied -55°C to +125°C

Supply Voltage to Ground Potential -0.5V to +7.0V

DC Voltage Applied to Outputs

in High-Z State -0.5V to +7.0V

DC Input Voltage -0.5V to +7.0V

DC Program Voltage 4.5 to 5.5V

Current into Outputs 16 mA

Static Discharge Voltage > 2001V
(per MIL-STD-883, Method 3015)

Latch-up Current > 200 mA

Operating Range^[2]

Range	Ambient Temperature ^[2]	Junction Temperature	Output Condition	V _{CC}	V _{CCO}
Commercial	0°C to +70°C	0°C to +90°C	5V	5V ± 0.25V	5V ± 0.25V
			3.3V	5V ± 0.25V	3.3V ± 0.3V
Industrial	-40°C to +85°C	-40°C to +105°C	5V	5V ± 0.5V	5V ± 0.5V
			3.3V	5V ± 0.5V	3.3V ± 0.3V
Military ^[3]	-55°C to +125°C	-55°C to +130°C	5V	5V ± 0.5V	5V ± 0.5V
			3.3V	5V ± 0.5V	3.3V ± 0.3V

5.0V Device Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditions	Min.	Typ.	Max.	Unit
V _{OH}	Output HIGH Voltage	V _{CC} = Min. I _{OH} = -3.2 mA (Com'I/Ind) ^[4] I _{OH} = -2.0 mA (Mil) ^[4]	2.4 2.4			V
V _{OHZ}	Output HIGH Voltage with Output Disabled ^[5]	V _{CC} = Max. I _{OH} = 0 μA (Com'I) ^[6] I _{OH} = 0 μA (Ind/Mil) ^[6] I _{OH} = -100 μA (Com'I) ^[6] I _{OH} = -150 μA (Ind/Mil) ^[6]			4.2 4.5 3.6 3.6	V
V _{OL}	Output LOW Voltage	V _{CC} = Min. I _{OL} = 16 mA (Com'I/Ind) ^[4] I _{OL} = 12 mA (Mil) ^[4]			0.5 0.5	V
V _{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs ^[7]	2.0		V _{CCmax}	V
V _{IL}	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs ^[7]	-0.5		0.8	V
I _{IX}	Input Load Current	V _I = GND OR V _{CC} , Bus-Hold Disabled	-10		10	μA
I _{OZ}	Output Leakage Current	V _O = GND or V _{CC} , Output Disabled, Bus-Hold Disabled	-50		50	μA
I _{OS}	Output Short Circuit Current ^[5, 8]	V _{CC} = Max., V _{OUT} = 0.5V	-30		-160	mA
I _{BHL}	Input Bus-Hold LOW Sustaining Current	V _{CC} = Min., V _{IL} = 0.8V	+75			μA
I _{BHH}	Input Bus-Hold HIGH Sustaining Current	V _{CC} = Min., V _{IH} = 2.0V	-75			μA
I _{BHLO}	Input Bus-Hold LOW Overdrive Current	V _{CC} = Max.			+500	μA
I _{BHHO}	Input Bus-Hold HIGH Overdrive Current	V _{CC} = Max.			-500	μA

Notes:

- Normal Programming Conditions apply across Ambient Temperature Range for specified programming methods. For more information on programming the Ultra37000 Family devices, please refer to the Application Note titled "An Introduction to In System Reprogramming with the Ultra37000."
- T_A is the "Instant On" case temperature.
- I_{OH} = -2 mA, I_{OL} = 2 mA for TDO.
- Tested initially and after any design or process changes that may affect these parameters.
- When the I/O is output disabled, the bus-hold circuit can weakly pull the I/O to above 3.6V if no leakage current is allowed. Note that all I/Os are output disabled during ISR programming. Refer to the application note "Understanding Bus-Hold" for additional information.
- These are absolute values with respect to device ground. All overshoots due to system or tester noise are included.
- Not more than one output should be tested at a time. Duration of the short circuit should not exceed 1 second. V_{OUT} = 0.5V has been chosen to avoid test problems caused by tester ground degradation.

Inductance^[5]

Parameter	Description	Test Conditions	44-Lead TQFP	44-Lead PLCC	44-Lead CLCC	84-Lead PLCC	84-Lead CLCC	100-Lead TQFP	160-Lead TQFP	208-Lead PQFP	Unit
L	Maximum Pin Inductance	$V_{IN} = 5.0V$ at $f = 1\text{ MHz}$	2	5	2	8	5	8	9	11	nH

Capacitance^[5]

Parameter	Description	Test Conditions	Max.	Unit
$C_{I/O}$	Input/Output Capacitance	$V_{IN} = 5.0V$ at $f = 1\text{ MHz}$ at $T_A = 25^\circ C$	10	pF
C_{CLK}	Clock Signal Capacitance	$V_{IN} = 5.0V$ at $f = 1\text{ MHz}$ at $T_A = 25^\circ C$	12	pF
C_{DP}	Dual-Function Pins ^[9]	$V_{IN} = 5.0V$ at $f = 1\text{ MHz}$ at $T_A = 25^\circ C$	16	pF

Endurance Characteristics^[5]

Parameter	Description	Test Conditions	Min.	Typ.	Unit
N	Minimum Reprogramming Cycles	Normal Programming Conditions ^[2]	1,000	10,000	Cycles

3.3V Device Characteristics
Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature $-65^\circ C$ to $+150^\circ C$

Ambient Temperature with

Power Applied $-55^\circ C$ to $+125^\circ C$

Supply Voltage to Ground Potential $-0.5V$ to $+4.6V$

DC Voltage Applied to Outputs

in High-Z State $-0.5V$ to $+7.0V$

DC Input Voltage $-0.5V$ to $+7.0V$

DC Program Voltage 3.0 to $3.6V$

Current into Outputs 8 mA

Static Discharge Voltage $> 2001V$
(per MIL-STD-883, Method 3015)

Latch-up Current $> 200\text{ mA}$

Operating Range^[2]

Range	Ambient Temperature ^[2]	Junction Temperature	V_{CC} ^[10]
Commercial	$0^\circ C$ to $+70^\circ C$	$0^\circ C$ to $+90^\circ C$	$3.3V \pm 0.3V$
Industrial	$-40^\circ C$ to $+85^\circ C$	$-40^\circ C$ to $+105^\circ C$	$3.3V \pm 0.3V$
Military ^[3]	$-55^\circ C$ to $+125^\circ C$	$-55^\circ C$ to $+130^\circ C$	$3.3V \pm 0.3V$

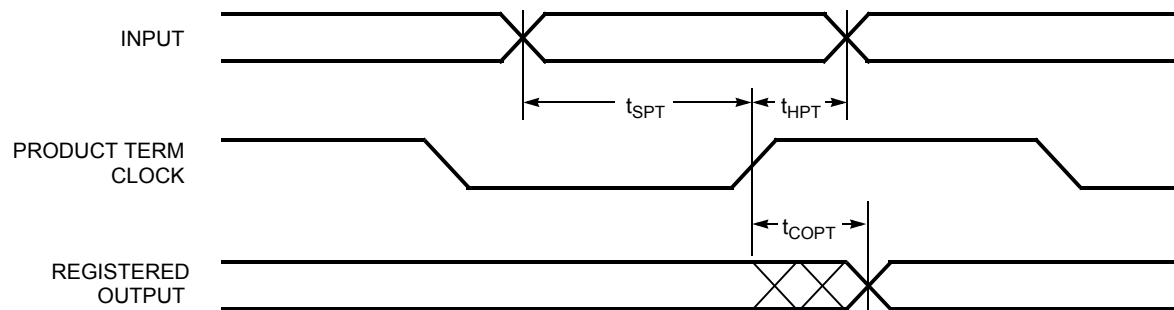
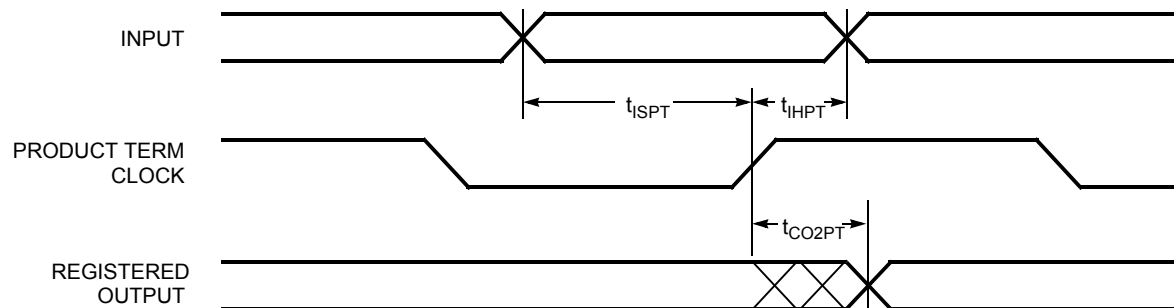
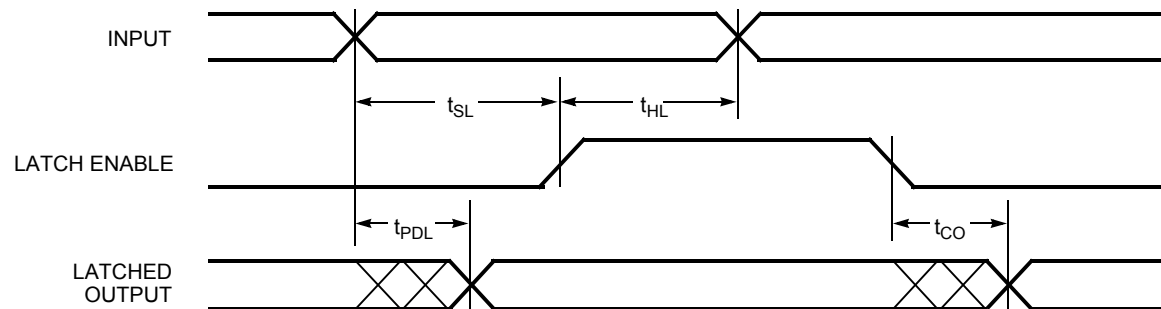
3.3V Device Electrical Characteristics Over the Operating Range

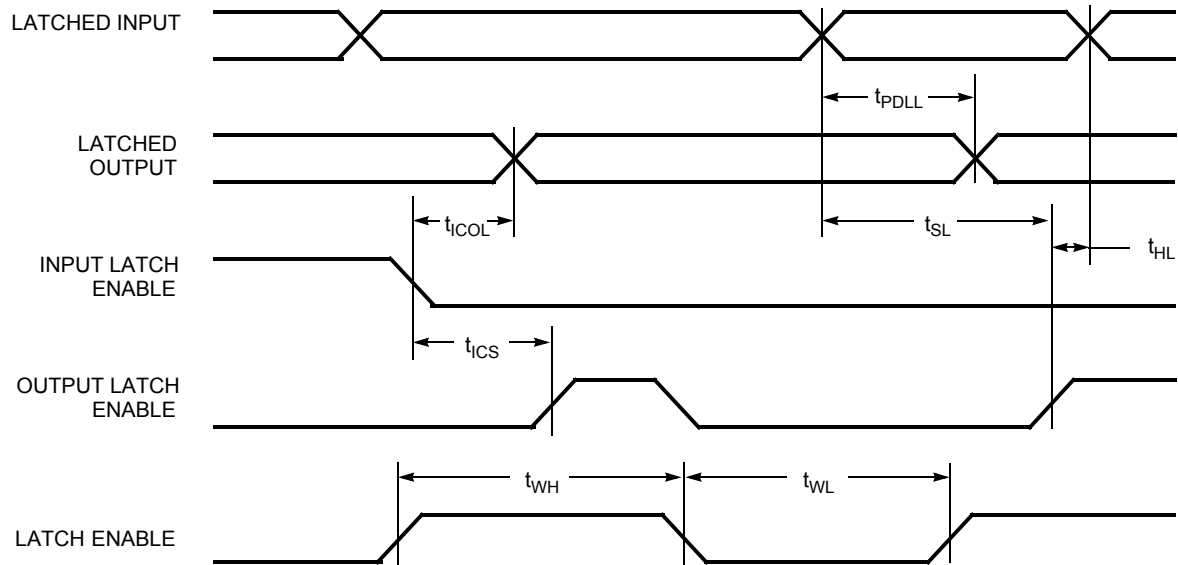
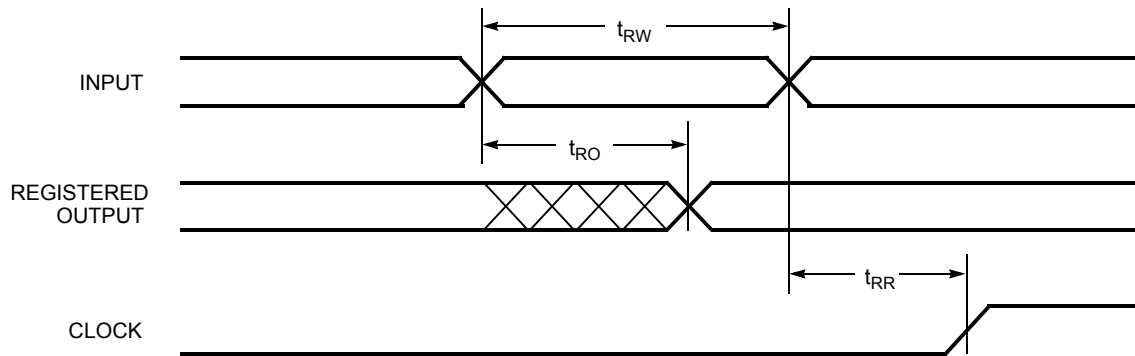
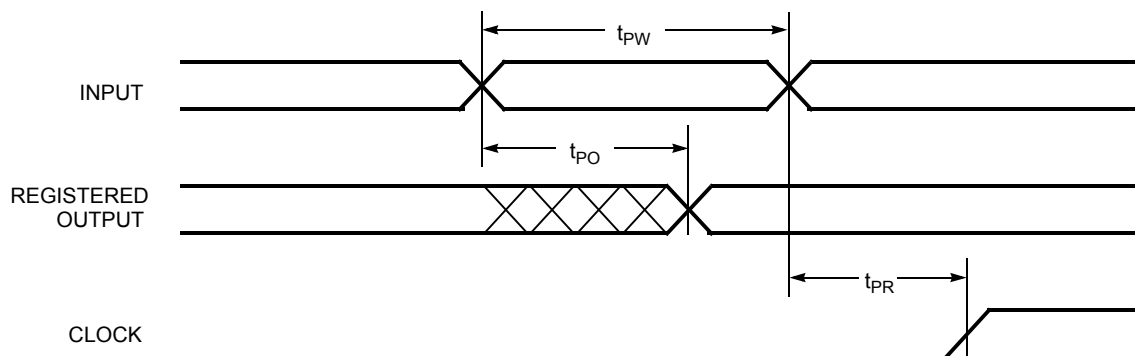
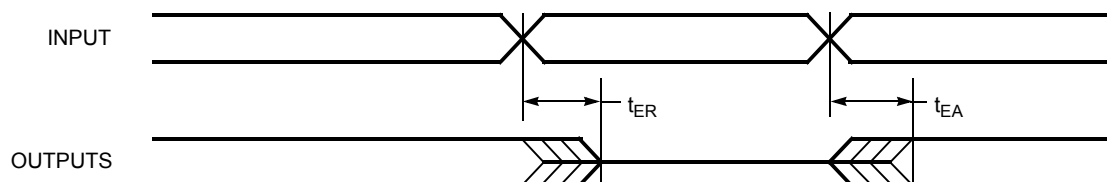
Parameter	Description	Test Conditions	Min.	Max.	Unit
V_{OH}	Output HIGH Voltage	$V_{CC} = \text{Min.}$ $I_{OH} = -4\text{ mA (Com'I)}^{[4]}$ $I_{OH} = -3\text{ mA (Mil)}^{[4]}$	2.4		V
V_{OL}	Output LOW Voltage	$V_{CC} = \text{Min.}$ $I_{OL} = 8\text{ mA (Com'I)}^{[4]}$ $I_{OL} = 6\text{ mA (Mil)}^{[4]}$		0.5	V
V_{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs ^[7]	2.0	5.5	V
V_{IL}	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs ^[7]	-0.5	0.8	V
I_{IX}	Input Load Current	$V_I = \text{GND OR } V_{CC}$, Bus-Hold Disabled	-10	10	μA
I_{OZ}	Output Leakage Current	$V_O = \text{GND or } V_{CC}$, Output Disabled, Bus-Hold Disabled	-50	50	μA
I_{OS}	Output Short Circuit Current ^[5, 8]	$V_{CC} = \text{Max.}$, $V_{OUT} = 0.5V$	-30	-160	mA
I_{BHL}	Input Bus-Hold LOW Sustaining Current	$V_{CC} = \text{Min.}$, $V_{IL} = 0.8V$	+75		μA
I_{BHH}	Input Bus-Hold HIGH Sustaining Current	$V_{CC} = \text{Min.}$, $V_{IH} = 2.0V$	-75		μA
I_{BHLO}	Input Bus-Hold LOW Overdrive Current	$V_{CC} = \text{Max.}$		+500	μA
I_{BHHO}	Input Bus-Hold HIGH Overdrive Current	$V_{CC} = \text{Max.}$		-500	μA

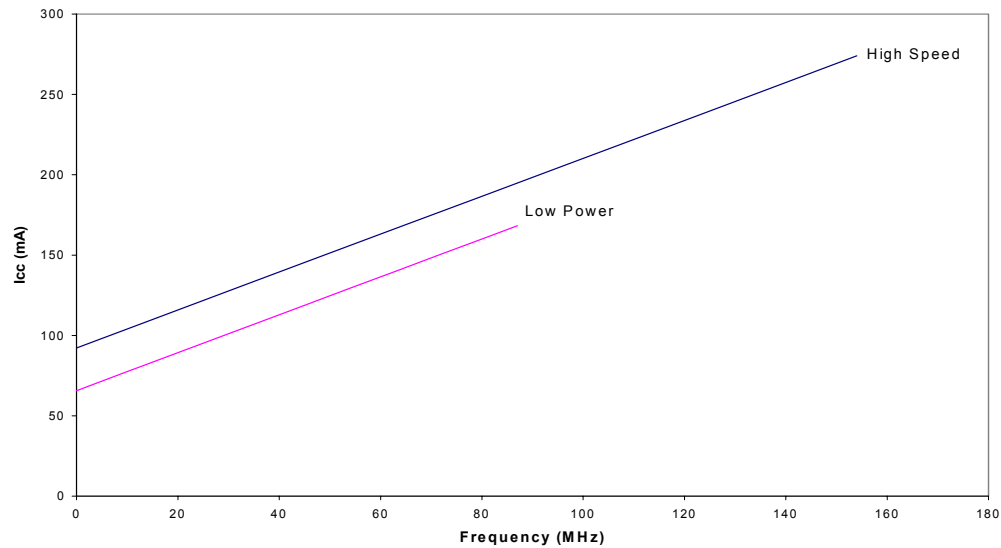
Notes:

9. Dual pins are I/O with JTAG pins.

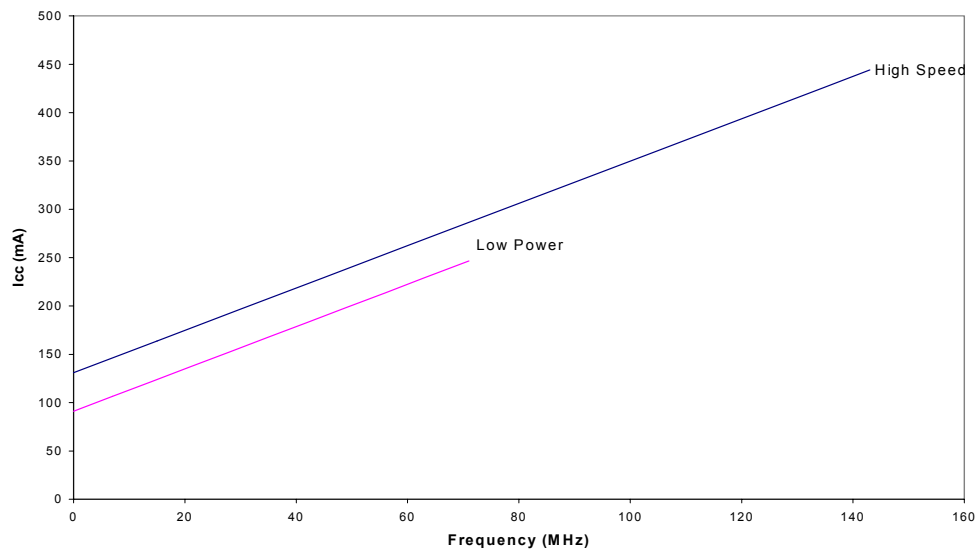
10. For CY37064VP100-143AC, CY37064VP100-143BBC, CY37064VP44-143AC, CY37064VP48-143BAC; Operating Range: V_{CC} is $3.3V \pm 0.16V$.

Switching Waveforms (continued)
Registered Output with Product Term Clocking Input Going Through the Array

Registered Output with Product Term Clocking Input Coming From Adjacent Buried Register

Latched Output


Switching Waveforms (continued)
Latched Input and Output

Asynchronous Reset

Asynchronous Preset

Output Enable/Disable


Typical 5.0V Power Consumption (continued)
CY37256


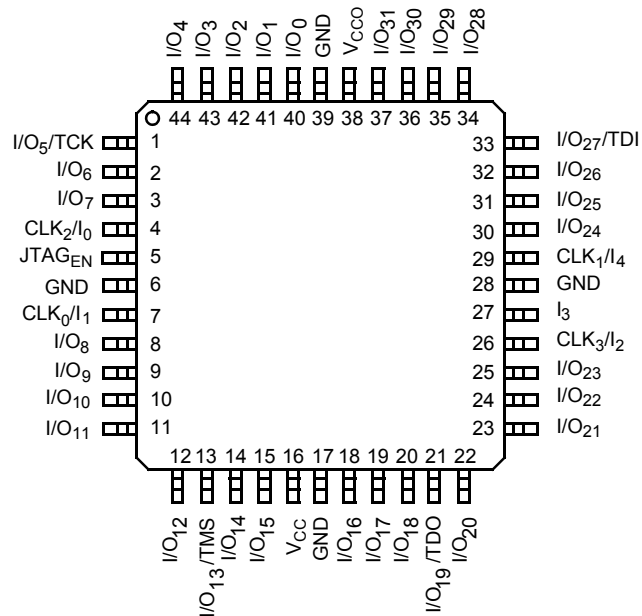
The typical pattern is a 16-bit up counter, per logic block, with outputs disabled.
 $V_{CC} = 5.0V$, $T_A = \text{Room Temperature}$

CY37384


The typical pattern is a 16-bit up counter, per logic block, with outputs disabled.
 $V_{CC} = 5.0V$, $T_A = \text{Room Temperature}$

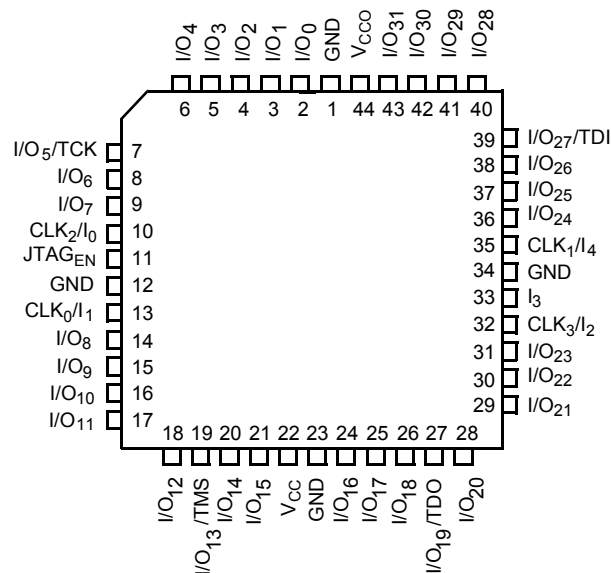
44-pin TQFP (A44)

Top View



44-pin PLCC (J67) / CLCC (Y67)

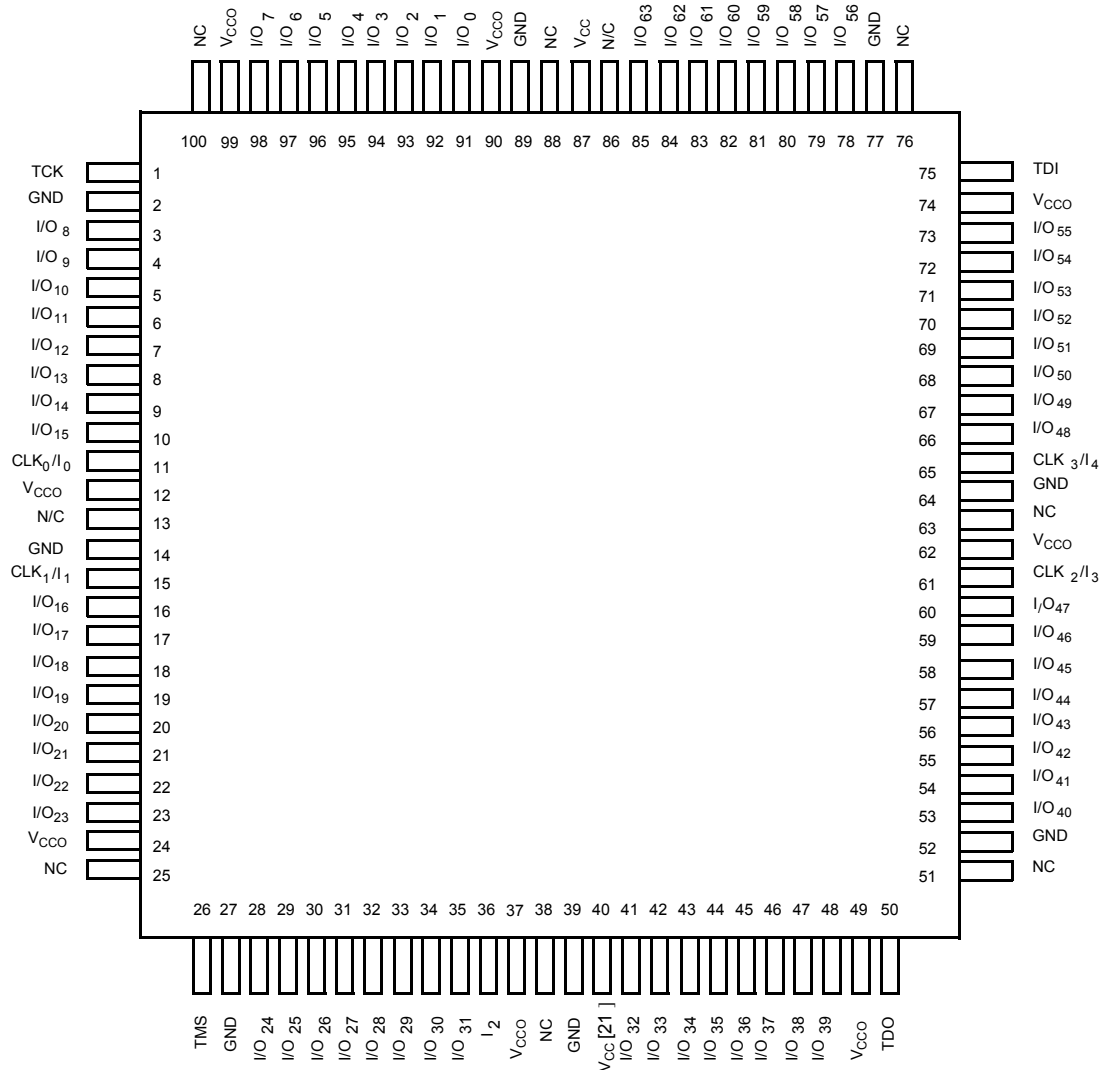
Top View

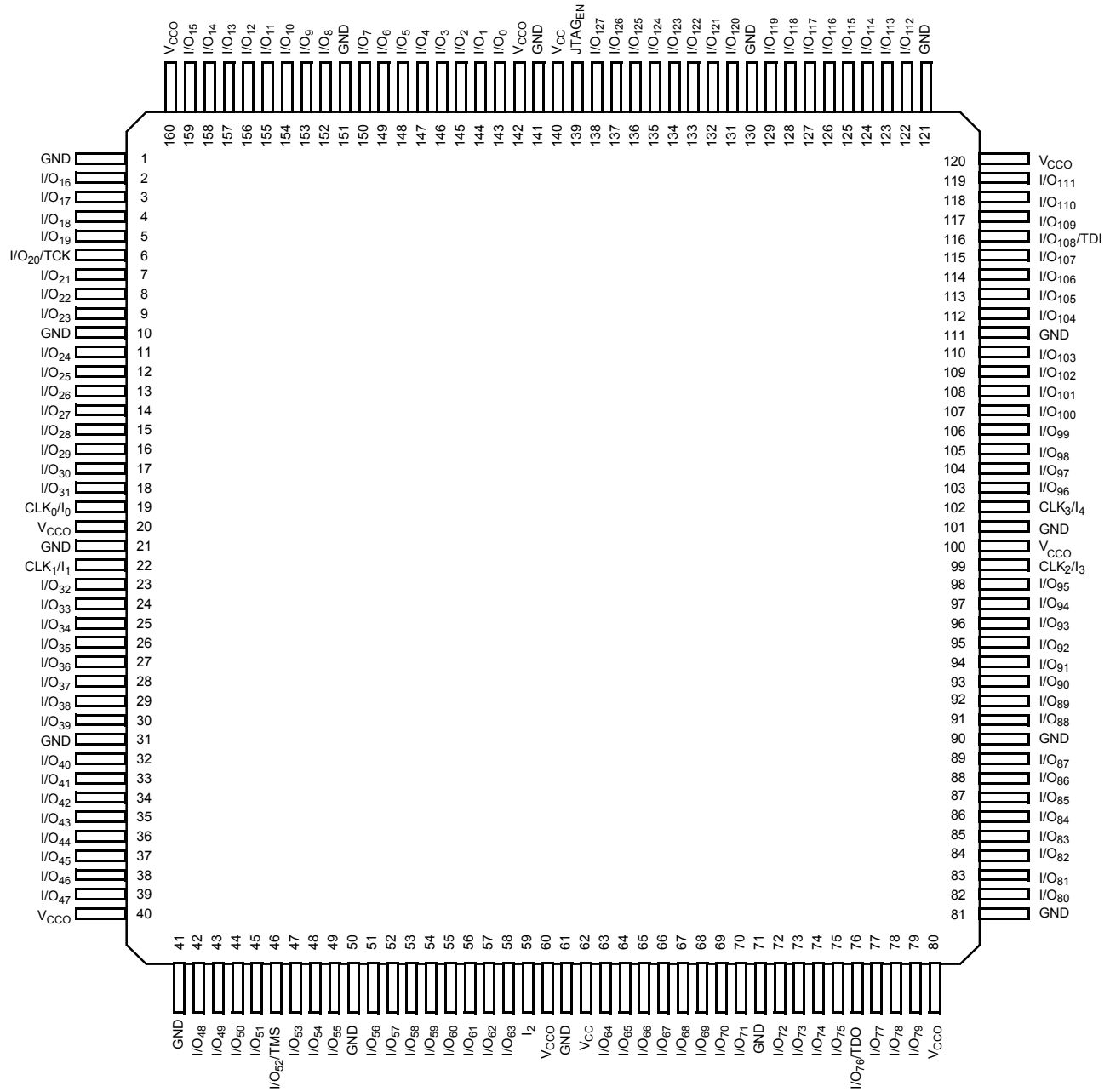


Pin Configurations^[20] (continued)

100-lead TQFP (A100)

Top View



Pin Configurations^[20] (continued)
**160-Lead TQFP (A160) / CQFP (U162)
for CY37128(V) and CY37256(V)
Top View**


Pin Configurations^[20] (continued)
**292-Ball PBGA (BG292)
Top View**

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	
A	GND	I/O ₂₁	NC	I/O ₁₆	I/O ₁₂	I/O ₉	I/O ₇	I/O ₄	I/O ₀	I/O ₁₉₀	I/O ₁₈₉	I/O ₁₈₆	I/O ₁₈₂	NC	I/O ₁₇₈	I/O ₁₇₅	NC	NC	I/O ₁₆₉	I/O ₁₆₈	A
B	I/O ₂₃	I/O ₂₀	I/O ₁₉	I/O ₁₈	I/O ₁₅	I/O ₁₁	I/O ₈	I/O ₅	I/O ₁	I/O ₁₉₁	I/O ₁₈₇	I/O ₁₈₅	I/O ₁₈₁	NC	NC	I/O ₁₇₄	I/O ₁₇₁	I/O ₁₇₀	NC	I/O ₁₆₆	B
C	NC	NC	I/O ₂₂	NC	I/O ₁₇	I/O ₁₄	I/O ₁₀	I/O ₆	I/O ₂	NC	I/O ₁₈₈	I/O ₁₈₄	I/O ₁₈₀	I/O ₁₇₉	I/O ₁₇₆	I/O ₁₇₃	I/O ₁₇₂	I/O ₁₆₇	I/O ₁₆₅	I/O ₁₆₂	C
D	I/O ₂₄	NC	NC	GND	NC	V _{CC0}	I/O ₁₃	GND	I/O ₃	NC	V _{CC}	I/O ₁₈₃	GND	I/O ₁₇₇	V _{CC0}	NC	GND	I/O ₁₆₄	TDI	I/O ₁₆₀	D
E	I/O ₂₇	I/O ₂₆	I/O ₂₅	NC													I/O ₁₆₃	I/O ₁₆₁	I/O ₁₅₉	I/O ₁₅₆	E
F	I/O ₃₀	TCK	I/O ₂₈	V _{CC0}													V _{CC0}	I/O ₁₅₈	NC	I/O ₁₅₄	F
G	I/O ₃₃	I/O ₃₂	I/O ₃₁	I/O ₂₉													I/O ₁₅₇	I/O ₁₅₅	I/O ₁₅₃	I/O ₁₅₂	G
H	I/O ₃₅	NC	I/O ₃₄	GND	GND												GND	I/O ₁₅₁	I/O ₁₅₀	I/O ₁₄₉	H
J	I/O ₃₉	I/O ₃₈	I/O ₃₇	I/O ₃₆	GND												I/O ₁₄₈	I/O ₁₄₇	I/O ₁₄₆	I/O ₁₄₅	J
K	I/O ₄₂	I/O ₄₀	I/O ₄₁	V _{CC}	GND												I/O ₁₄₄	CLK ₃ /I ₄	NC	NC	K
L	I/O ₄₃	I/O ₄₄	I/O ₄₅	I/O ₄₆	GND												V _{CC}	CLK ₂ /I ₃	I/O ₁₄₃	NC	L
M	I/O ₄₇	CLK ₀ /I ₀	CLK ₁ /I ₁	I/O ₄₈	GND												I/O ₁₃₉	I/O ₁₄₀	I/O ₁₄₁	I/O ₁₄₂	M
N	I/O ₄₉	I/O ₅₀	I/O ₅₁	GND	GND												GND	I/O ₁₃₆	I/O ₁₃₇	I/O ₁₃₈	N
P	I/O ₅₂	I/O ₅₃	I/O ₅₅	I/O ₅₈													I/O ₁₃₁	I/O ₁₃₃	I/O ₁₃₄	I/O ₁₃₅	P
R	I/O ₅₄	I/O ₅₆	I/O ₅₉	V _{CC0}													V _{CC0}	I/O ₁₃₀	NC	I/O ₁₃₂	R
T	I/O ₅₇	I/O ₆₀	I/O ₆₂	I/O ₆₅													I/O ₁₂₄	I/O ₁₂₇	I/O ₁₂₈	I/O ₁₂₉	T
U	I/O ₆₁	I/O ₆₃	I/O ₆₆	GND	I/O ₇₆	V _{CC0}	I/O ₈₂	GND	I/O ₉₁	V _{CC}	I/O ₉₈	I/O ₁₀₂	GND	I/O ₁₁₂	V _{CC0}	NC	GND	I/O ₁₂₃	I/O ₁₂₂	I/O ₁₂₆	U
V	I/O ₆₄	I/O ₆₇	I/O ₆₉	I/O ₇₅	I/O ₇₈	I/O ₈₁	I/O ₈₅	I/O ₈₈	I/O ₉₂	I ₂	I/O ₉₇	I/O ₁₀₁	I/O ₁₀₅	I/O ₁₀₉	I/O ₁₁₃	TD0	I/O ₁₁₄	I/O ₁₁₇	I/O ₁₂₁	I/O ₁₂₅	V
W	I/O ₆₈	I/O ₇₀	I/O ₇₂	I/O ₇₄	I/O ₇₉	I/O ₈₃	I/O ₈₆	I/O ₈₉	I/O ₉₃	I/O ₉₅	I/O ₉₆	I/O ₁₀₀	I/O ₁₀₄	I/O ₁₀₇	I/O ₁₁₀	NC	NC	I/O ₁₁₅	I/O ₁₁₈	I/O ₁₂₀	W
Y	I/O ₇₁	I/O ₇₃	I/O ₇₇	TMS	I/O ₈₀	I/O ₈₄	I/O ₈₇	I/O ₉₀	I/O ₉₄	NC	NC	I/O ₉₉	I/O ₁₀₃	I/O ₁₀₆	I/O ₁₀₈	I/O ₁₁₁	NC	NC	I/O ₁₁₆	I/O ₁₁₉	Y
	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	



Pin Configurations^[20] (continued)

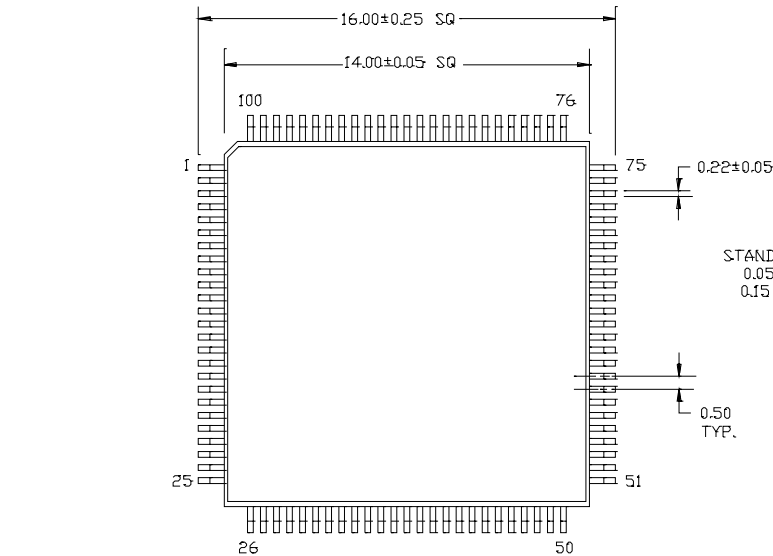
400-Ball Fine-Pitch BGA (BB400)

Top View

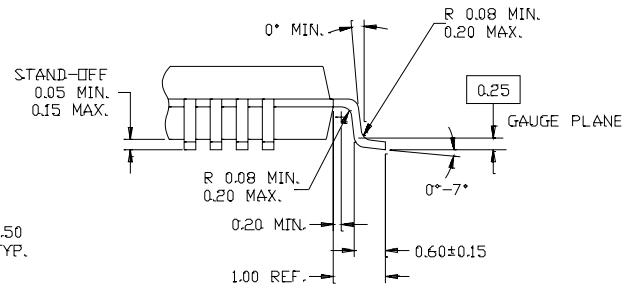
A	GND	GND	NC	I/O ₁₇	I/O ₁₆	I/O ₁₄	I/O ₂₉	V _{CC}	I/O ₁₁	GND	GND	I/O ₂₅₇	V _{CC}	I/O ₂₃₉	I/O ₂₃₃	I/O ₂₃₂	I/O ₂₃₀	NC	GND	GND
B	GND	GND	GND	NC	I/O ₁₅	I/O ₁₃	I/O ₂₈	V _{CC}	I/O ₁₀	GND	GND	I/O ₂₅₆	V _{CC}	I/O ₂₃₈	I/O ₂₃₁	I/O ₂₂₉	NC	GND	GND	GND
C	NC	GND	GND	GND	I/O ₂₀	I/O ₁₂	I/O ₂₇	V _{CC}	I/O ₉	GND	GND	I/O ₂₅₅	V _{CC}	I/O ₂₃₇	I/O ₂₂₈	I/O ₂₄₅	GND	GND	GND	NC
D	I/O ₄₄	NC	GND	I/O ₂₁	I/O ₁₉	I/O ₁₈	I/O ₂₆	I/O ₂₅	I/O ₈	GND	GND	I/O ₂₅₄	I/O ₂₃₅	I/O ₂₃₆	I/O ₂₅₁	I/O ₂₄₄	I/O ₂₄₃	GND	NC	I/O ₂₂₇
E	I/O ₄₆	I/O ₄₃	I/O ₂₃	I/O ₂₂	NC	I/O ₃₅	I/O ₃₄	I/O ₂₄	I/O ₇	I/O ₄	I/O ₂₆₃	I/O ₂₅₃	I/O ₂₃₄	I/O ₂₅₀	I/O ₂₄₈	NC	I/O ₂₄₁	I/O ₂₄₂	I/O ₂₂₅	I/O ₂₂₆
F	I/O ₄₇	I/O ₄₅	I/O ₄₂	I/O ₄₁	I/O ₄₀	NC	I/O ₃₃	I/O ₃₂	I/O ₆	I/O ₃	I/O ₂₆₂	I/O ₂₅₂	I/O ₂₄₉	I/O ₂₄₇	I/O ₂₂₀	I/O ₂₂₁	I/O ₂₄₀	I/O ₂₂₂	I/O ₂₂₃	I/O ₂₂₄
G	I/O ₅₃	I/O ₅₂	I/O ₅₁	I/O ₅₀	I/O ₃₉	I/O ₃₈	I/O ₃₇	I/O ₃₁	I/O ₅	I/O ₂	I/O ₂₆₁	V _{CC}	I/O ₂₄₆	I/O ₂₁₇	I/O ₂₁₈	I/O ₂₁₉	I/O ₂₁₂	I/O ₂₁₃	I/O ₂₁₄	I/O ₂₁₅
H	V _{CC}	V _{CC}	V _{CC}	I/O ₄₉	I/O ₄₈	I/O ₃₆	TCK	V _{CC}	I/O ₃₀	I/O ₁	I/O ₂₅₉	I/O ₂₆₀	V _{CC}	TDI	I/O ₂₁₆	I/O ₂₁₀	I/O ₂₁₁	V _{CC}	V _{CC}	V _{CC}
J	I/O ₅₉	I/O ₅₈	I/O ₅₇	I/O ₅₆	I/O ₅₅	I/O ₅₄	V _{CC}	I/O ₆₂	I/O ₆₀	I/O ₀	I/O ₂₅₈	I/O ₂₀₂	I/O ₂₀₃	CLK ₃ /I ₄	I/O ₂₀₄	I/O ₂₀₅	I/O ₂₀₆	I/O ₂₀₇	I/O ₂₀₈	I/O ₂₀₉
K	GND	GND	GND	GND	I/O ₆₅	I/O ₆₄	CLK ₀ /I ₀	I/O ₆₃	I/O ₆₁	GND	GND	I/O ₁₉₈	I/O ₁₉₉	CLK ₂ /I ₃	I/O ₂₀₀	I/O ₂₀₁	GND	GND	GND	GND
L	GND	GND	GND	GND	I/O ₆₉	I/O ₆₈	NC	I/O ₆₇	I/O ₆₆	GND	GND	I/O ₁₉₃	I/O ₁₉₅	I ₂	I/O ₁₉₆	I/O ₁₉₇	GND	GND	GND	GND
M	I/O ₈₉	I/O ₈₈	I/O ₈₇	I/O ₈₆	I/O ₈₅	I/O ₈₄	CLK ₁ /I ₁	I/O ₇₁	I/O ₇₀	I/O ₁₂₆	I/O ₁₃₂	I/O ₁₉₂	I/O ₁₉₄	V _{CC}	I/O ₁₇₄	I/O ₁₇₅	I/O ₁₇₆	I/O ₁₇₇	I/O ₁₇₈	I/O ₁₇₉
N	V _{CC}	V _{CC}	V _{CC}	I/O ₉₁	I/O ₉₀	I/O ₇₂	TMS	V _{CC}	I/O ₁₂₈	I/O ₁₂₇	I/O ₁₃₃	I/O ₁₆₂	V _{CC}	TDO	I/O ₁₈₀	I/O ₁₆₈	I/O ₁₆₉	V _{CC}	V _{CC}	V _{CC}
P	I/O ₉₅	I/O ₉₄	I/O ₉₃	I/O ₉₂	I/O ₇₅	I/O ₇₄	I/O ₇₃	I/O ₁₁₄	V _{CC}	I/O ₁₂₉	I/O ₁₃₄	I/O ₁₃₇	I/O ₁₆₃	I/O ₁₈₁	I/O ₁₈₂	I/O ₁₈₃	I/O ₁₇₀	I/O ₁₇₁	I/O ₁₇₂	I/O ₁₇₃
R	I/O ₉₀	I/O ₇₉	I/O ₇₈	I/O ₁₀₈	I/O ₇₇	I/O ₇₆	I/O ₁₁₅	I/O ₁₁₇	I/O ₁₂₀	I/O ₁₃₀	I/O ₁₃₅	I/O ₁₃₈	I/O ₁₆₄	I/O ₁₆₅	NC	I/O ₁₈₄	I/O ₁₈₅	I/O ₁₈₆	I/O ₁₈₉	I/O ₁₉₁
T	I/O ₈₂	I/O ₈₁	I/O ₁₁₀	I/O ₁₀₉	NC	I/O ₁₁₆	I/O ₁₁₈	I/O ₁₀₂	I/O ₁₂₁	I/O ₁₃₁	I/O ₁₃₆	I/O ₁₃₉	I/O ₁₅₆	I/O ₁₆₆	I/O ₁₆₇	NC	I/O ₁₅₄	I/O ₁₅₅	I/O ₁₈₇	I/O ₁₉₀
U	I/O ₈₃	NC	GND	I/O ₁₁₁	I/O ₁₁₂	I/O ₁₁₉	I/O ₁₀₄	I/O ₁₀₃	I/O ₁₂₂	GND	GND	I/O ₁₄₀	I/O ₁₅₇	I/O ₁₅₈	I/O ₁₅₀	I/O ₁₅₁	I/O ₁₅₃	GND	NC	I/O ₁₈₈
V	NC	GND	GND	GND	I/O ₁₁₃	I/O ₉₆	I/O ₁₀₅	V _{CC}	I/O ₁₂₃	GND	GND	I/O ₁₄₁	V _{CC}	I/O ₁₅₉	I/O ₁₄ 4	I/O ₁₅₂	GND	GND	GND	NC
W	GND	GND	GND	NC	I/O ₉₇	I/O ₉₉	I/O ₁₀₆	V _{CC}	I/O ₁₂₄	GND	GND	I/O ₁₄₂	V _{CC}	I/O ₁₆₀	I/O ₁₄₅	I/O ₁₄₇	NC	GND	GND	GND
Y	GND	GND	NC	I/O ₉₈	I/O ₁₀₀	I/O ₁₀₁	I/O ₁₀₇	V _{CC}	I/O ₁₂₅	GND	GND	I/O ₁₄₃	V _{CC}	I/O ₁₆₁	I/O ₁₄₆	I/O ₁₄₈	I/O ₁₄₉	NC	GND	GND

Package Diagrams (continued)

100-Lead Lead (Pb)-Free Thin Plastic Quad Flat Pack (TQFP) A100



DIMENSIONS ARE IN MILLIMETERS.

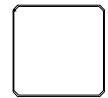


DETAIL A

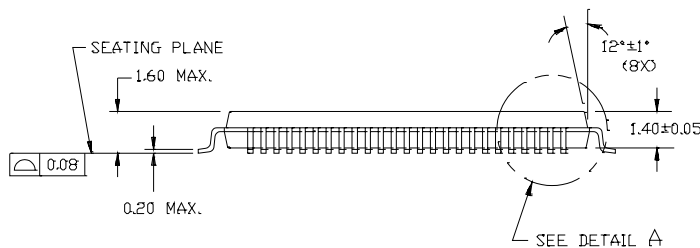
NOTE: PKG. CAN HAVE



OR



51-85048-*B

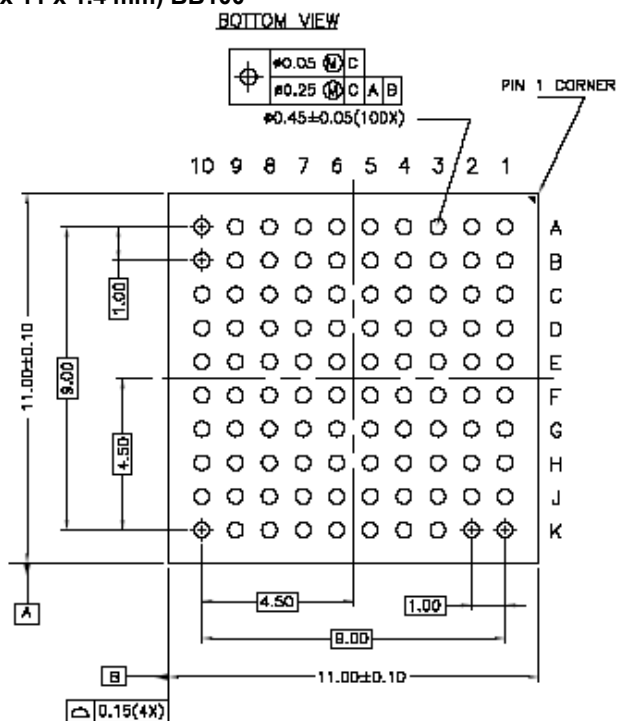
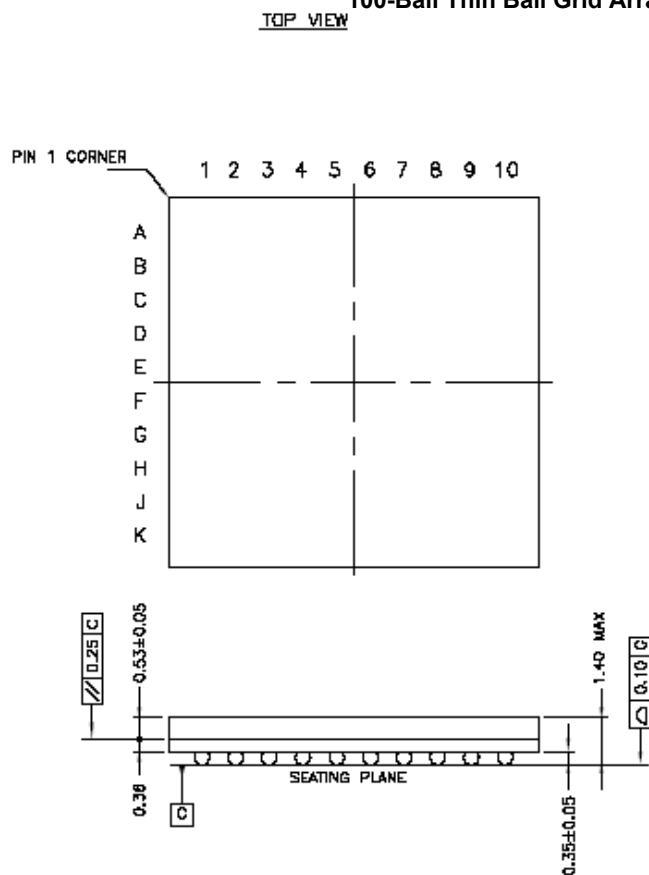




Ultra37000 CPLD Family

Package Diagrams (continued)

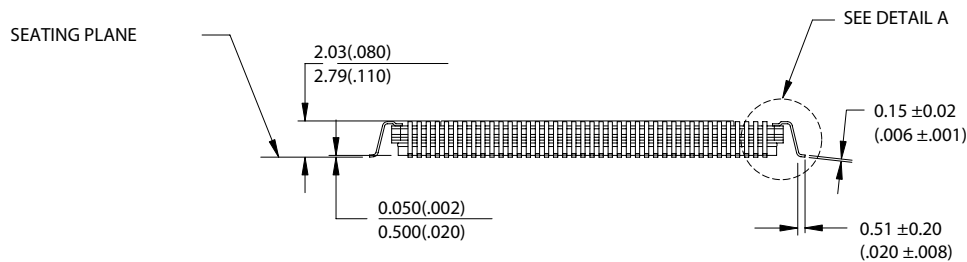
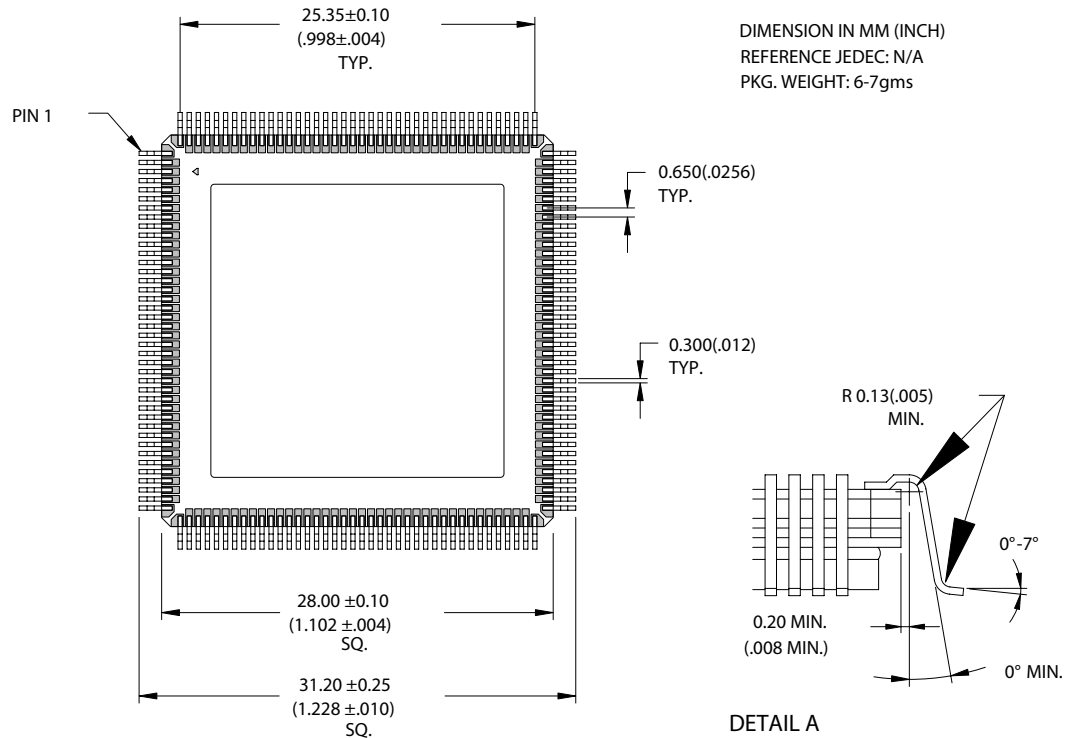
100-Ball Thin Ball Grid Array (11 x 11 x 1.4 mm) BB100



51-85107-*B

Package Diagrams (continued)

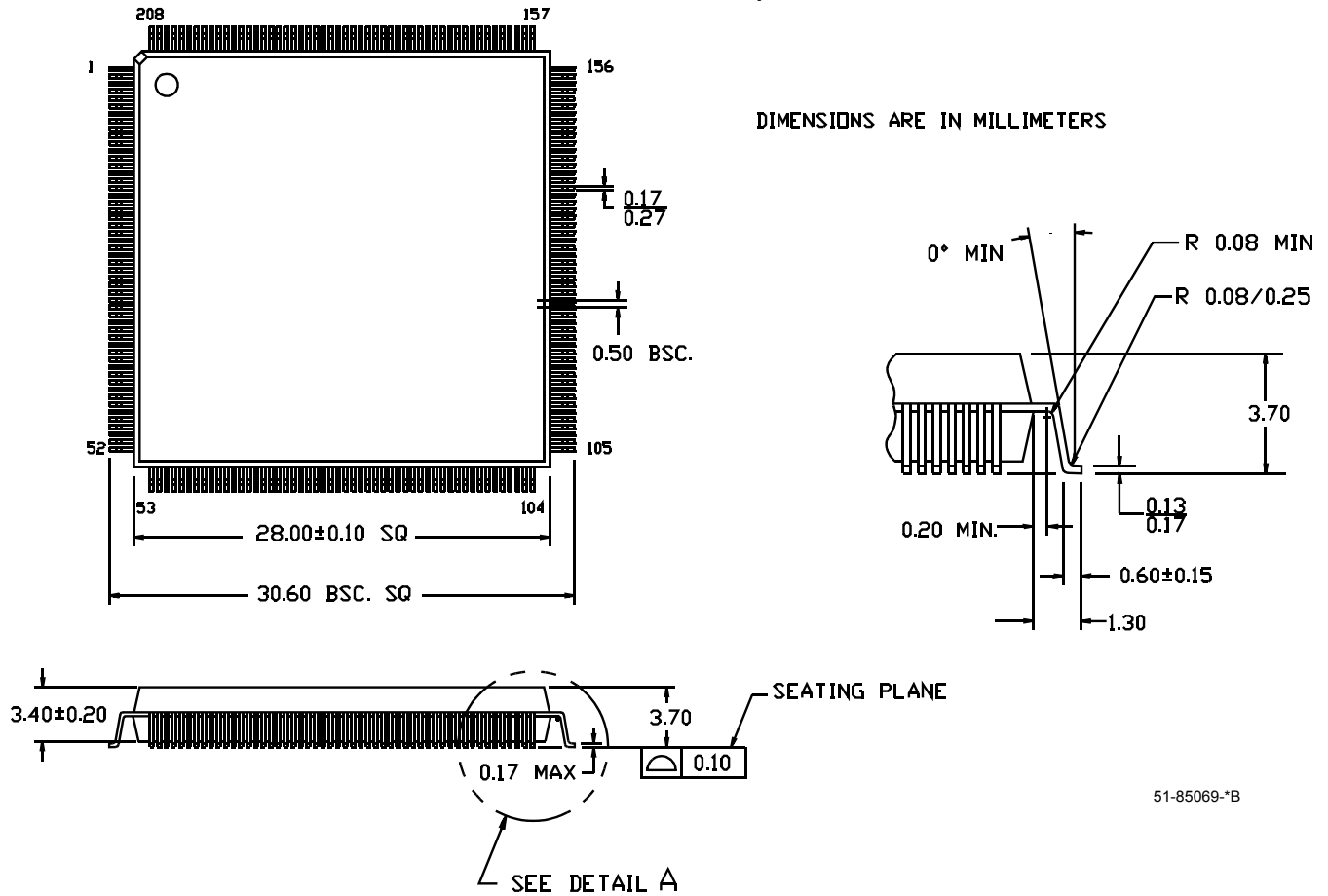
160-Lead Ceramic Quad Flatpack (Cavity Up) U162



51-80106-*A

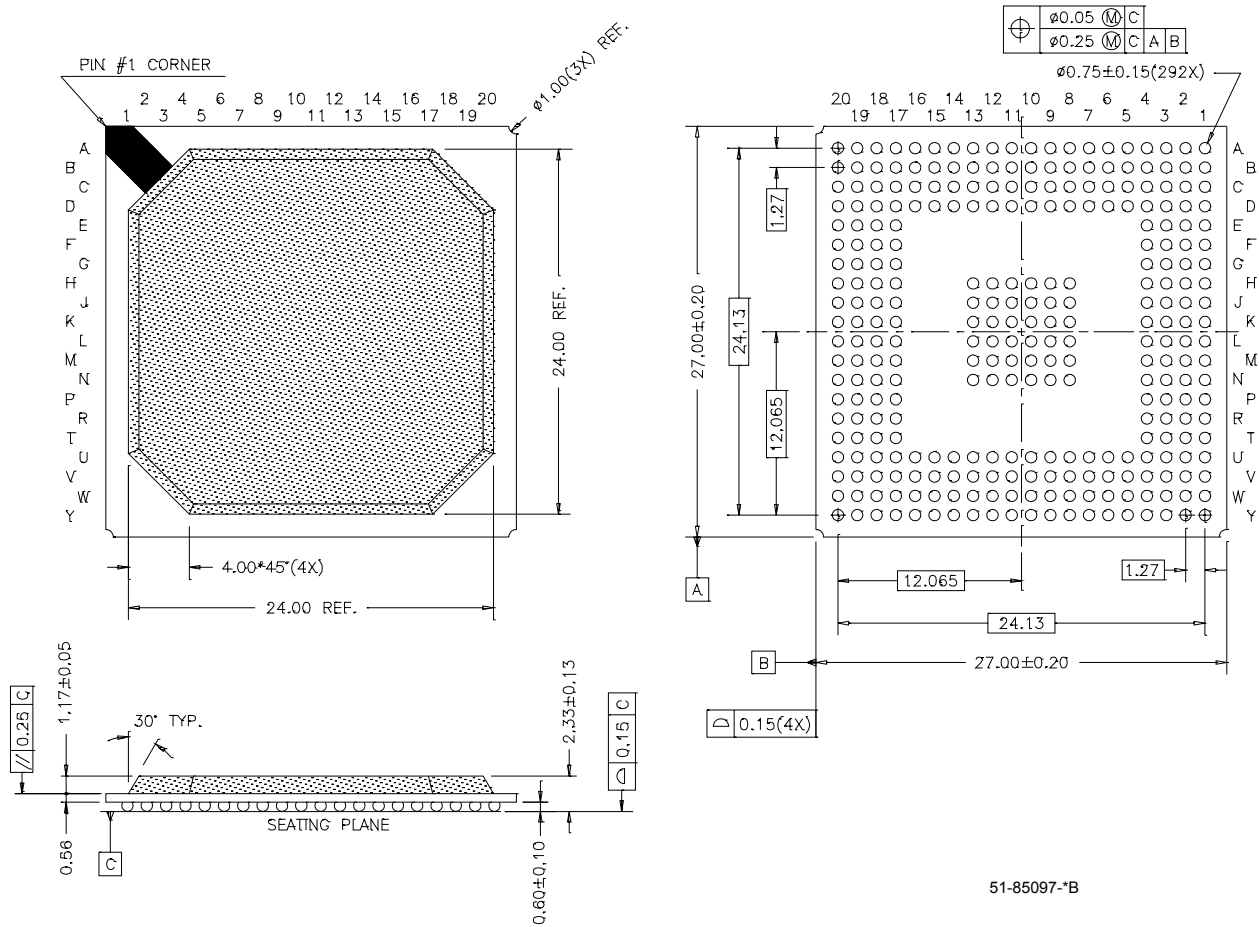
Package Diagrams (continued)

208-Lead Plastic Quad Flatpack N208



Package Diagrams (continued)

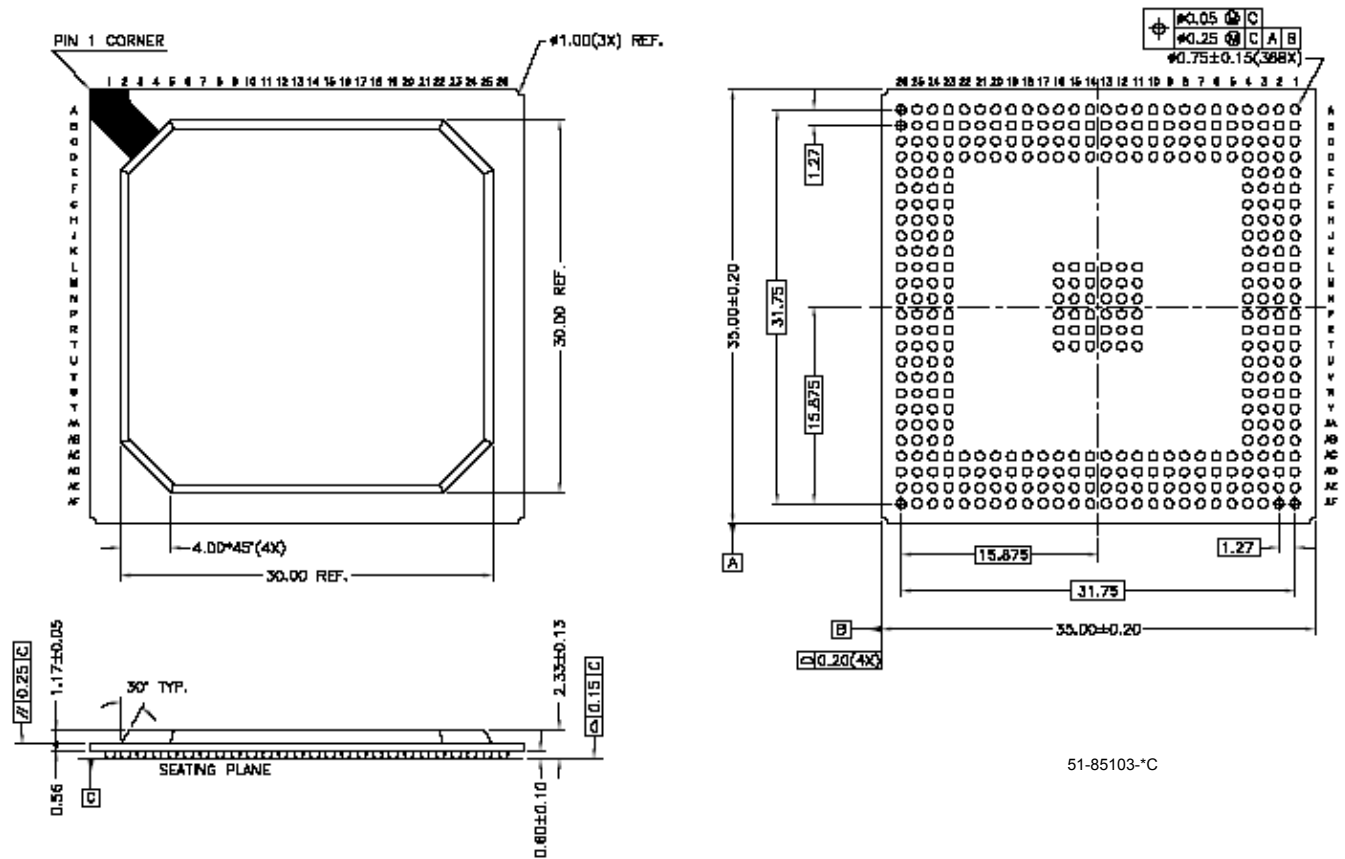
292-Ball Plastic Ball Grid Array PBGA (27 x 27 x 2.33 mm) BG292



51-85097-*B

Package Diagrams (continued)

388-Ball Plastic Ball Grid Array PBGA (35 x 35 x 2.33 mm) BG388



51-85103-°C

Addendum**3.3V Operating Range****(CY37064VP100-143AC, CY37064VP100-143BBC, CY37064VP44-143AC, CY37064VP48-143BAC)**

Range	Ambient Temperature ^[2]	Junction Temperature	V _{CC}
Commercial	0°C to +70°C	0°C to +90°C	3.3V ± 0.16V

Document History Page

Document Title: Ultra37000 CPLD Family 5V, 3.3V, ISR™ High-Performance CPLDs Document Number: 38-03007				
REV.	ECN NO.	Issue Date	Orig. of Change	Description of Change
**	106272	04/18/01	SZV	Change from Spec number: 38-00475 to 38-03007
*A	124942	03/21/03	OOR	Updated 3.3V V _{CC} requirements for –144 speeds Added an Addendum
*B	126262	05/09/03	TEH	Changed pinout for CY37128V BB100 package
*C	128125	07/16/03	HOM	Obsoleted following 3.3V PLCC packaged devices: CY37032VP44-143JC CY37032VP44-100JC CY37032VP44-100JI CY37064VP44-143JC CY37064VP84-143JC CY37064VP44-100JC CY37064VP84-100JC CY37064VP44-100JI CY37064VP84-100JI CY37128VP84-125JC CY37128VP84-83JC CY37128VP84-83JI
*D	282709	See ECN	YDT	Changed package diagrams and labels for consistency Added Lead (Pb)-free logo on first page, as well as a note in Features Added Lead (Pb)-free package diagram labels Added Lead-free Parts to Ordering Information CY37032P44-200AXC, CY37032P44-200JXC, CY37032P44-154AXI, CY37032P44-154JXI, CY37032P44-125AXC, CY37032P44-125JXC, CY37064P44-200AXC, CY37064P44-200JXC, CY37064P100-200AXC, CY37064P44-154AXI, CY37064P44-154JXI, CY37064P44-125AXC, CY37064P44-125JXC, CY37064P100-125AXC, CY37064P44-125AXI, CY37064P100-125AXI, CY37128P84-167JXC, CY37128P100-167AXC, CY37128P160-167AXC, CY37128P84-125JXC, CY37128P100-125AXC, CY37128P160-125AXC, CY37128P84-125JXI, CY37128P100-125AXI, CY37128P160-125AXI, CY37128P84-100JXC, CY37128P100-100AXC, CY37128P160-100AXC, CY37128P100-100AXI, CY37192P160-154AXC, CY37192P160-125AXC, CY37192P160-125AXI, CY37192P160-83AXC, CY37192P160-83AXI, CY37256P160-154AXC, CY37256P160-125AXC, CY37256P160-125AXI, CY37256P160-83AXC, CY37256P160-83AXI, CY37032VP44-143AXC, CY37032VP44-100AXC, CY37032VP44-100AXI, CY37032VP44-100JXI, CY37064VP44-143AXC, CY37064VP100-143AXC, CY37064VP44-100AXC, CY37064VP100-100AXC, CY37064VP44-100AXI, CY37064VP100-100AXI, CY37128VP100-125AXC, CY37128VP160-125AXC, CY37128VP160-125AXI, CY37128VP100-83AXC, CY37128VP160-83AXC, CY37128VP100-83AXI, CY37128VP160-83AXI, CY37192VP160-100AXC, CY37192VP160-66AXC, CY37256VP160-100AXC, CY37256VP160-100AXI, CY37256VP160-66AXC
*E	321635	See ECN	PCX	Added Package Diagram BG292 Updated all PBGA package type information (BG292 & BG388)